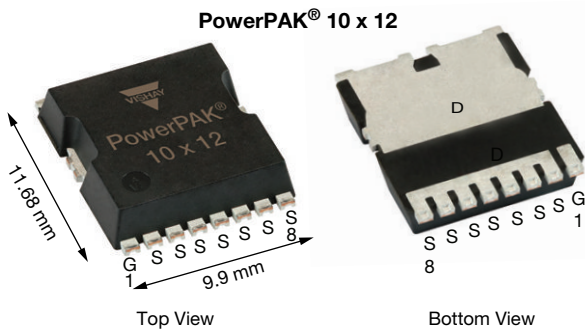


N-Channel 40 V (D-S) MOSFET

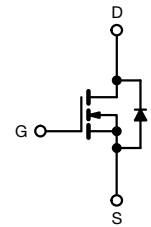

FEATURES

- TrenchFET® Gen V power MOSFET
- Leadership $R_{DS(on)}$ minimizes power loss from conduction
- 100 % R_{g} and UIS tested
- Standard level FET
- Enhance power dissipation and lower R_{thJC}
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912


RoHS
COMPLIANT
HALOGEN
FREE

APPLICATIONS

- Synchronous rectification
- Automation
- OR-ing and hot swap switch
- Power supplies
- Motor drive control
- Battery management



N-Channel MOSFET

PRODUCT SUMMARY

V_{DS} (V)	40
$R_{DS(on)}$ max. (Ω) at $V_{GS} = 10$ V	0.00047
Q_g typ. (nC)	312
I_D (A) ^a	795
Configuration	Single

ORDERING INFORMATION

Package	PowerPAK® 10 x 12
Lead (Pb)-free and halogen-free	SiJK140E-T1-GE3

ABSOLUTE MAXIMUM RATINGS ($T_A = 25$ °C, unless otherwise noted)

PARAMETER	SYMBOL	LIMIT	UNIT
Drain-source voltage	V_{DS}	40	V
Gate-source voltage	V_{GS}	± 20	
Continuous drain current ($T_J = 175$ °C)	$T_C = 25$ °C	795	A
	$T_C = 100$ °C	562	
	$T_A = 25$ °C	140 ^{b, c}	
	$T_A = 100$ °C	99 ^{b, c}	
Pulsed drain current ($t = 100$ μ s)	I_{DM}	900	A
Continuous source-drain diode current	$T_C = 25$ °C	487	
	$T_A = 25$ °C	15 ^{b, c}	
Single pulse avalanche current	I_{AS}	100	mJ
Single pulse avalanche energy	E_{AS}	500	
Maximum power dissipation	$T_C = 25$ °C	536	W
	$T_C = 100$ °C	268	
	$T_A = 25$ °C	17 ^{b, c}	
	$T_A = 100$ °C	8.3 ^{b, c}	
Operating junction and storage temperature range	T_J, T_{stg}	-55 to +175	°C
Soldering recommendations (peak temperature) ^c		260	

THERMAL RESISTANCE RATINGS

PARAMETER	SYMBOL	TYPICAL	MAXIMUM	UNIT
Maximum junction-to-ambient ^b	R_{thJA}	6.3	9	°C/W
Maximum junction-to-case (drain)	R_{thJC}	0.21	0.28	

Notes

- $T_C = 25$ °C
- Surface mounted on 1" x 1" FR4 board
- $t = 10$ s
- See solder profile (www.vishay.com/doc?73257). The PowerPAK 10 x 12 is a leadless package. The end of the lead terminal is exposed copper (not plated) as a result of the singulation process in manufacturing. A solder fillet at the exposed copper tip cannot be guaranteed and is not required to ensure adequate bottom side solder interconnection
- Rework conditions: manual soldering with a soldering iron is not recommended for leadless components
- Maximum under steady state conditions is 39 °C/W



SPECIFICATIONS ($T_J = 25\text{ }^\circ\text{C}$, unless otherwise noted)						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT
Static						
Drain-source breakdown voltage	V_{DS}	$V_{GS} = 0\text{ V}$, $I_D = 250\text{ }\mu\text{A}$	40	-	-	V
V_{DS} temperature coefficient	$\Delta V_{DS}/T_J$	$I_D = 10\text{ mA}$	-	22	-	mV/ $^\circ\text{C}$
$V_{GS(th)}$ temperature coefficient	$\Delta V_{GS(th)}/T_J$	$I_D = 250\text{ }\mu\text{A}$	-	-8.7	-	
Gate-source threshold voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}$, $I_D = 250\text{ }\mu\text{A}$	2.4	-	3.5	V
Gate-source leakage	I_{GSS}	$V_{DS} = 0\text{ V}$, $V_{GS} = \pm 20\text{ V}$	-	-	± 100	nA
Zero gate voltage drain current	I_{DSS}	$V_{DS} = 40\text{ V}$, $V_{GS} = 0\text{ V}$	-	-	1	μA
		$V_{DS} = 40\text{ V}$, $V_{GS} = 0\text{ V}$, $T_J = 55\text{ }^\circ\text{C}$	-	-	10	
Drain-source on-state resistance ^a	$R_{DS(on)}$	$V_{GS} = 10\text{ V}$, $I_D = 20\text{ A}$	-	0.00034	0.00047	Ω
Forward transconductance ^a	g_{fs}	$V_{DS} = 25\text{ V}$, $I_D = 100\text{ A}$	-	450	-	S
Dynamic ^b						
Input capacitance	C_{iss}	$V_{DS} = 20\text{ V}$, $V_{GS} = 0\text{ V}$, $f = 1\text{ MHz}$	-	18 510	-	μF
Output capacitance	C_{oss}		-	8540	-	
Reverse transfer capacitance	C_{rss}		-	555	-	
Total gate charge	Q_g	$V_{DS} = 40\text{ V}$, $V_{GS} = 10\text{ V}$, $I_D = 20\text{ A}$	-	312	470	nC
Gate-source charge	Q_{gs}		-	84	-	
Gate-drain charge	Q_{gd}		-	70	-	
Output charge	Q_{oss}	$V_{DS} = 20\text{ V}$, $V_{GS} = 0\text{ V}$	-	220	-	
Gate resistance	R_g	$f = 1\text{ MHz}$	0.22	1.1	2.2	Ω
Turn-on delay time	$t_{d(on)}$	$V_{DD} = 20\text{ V}$, $R_L = 4\text{ }\Omega$, $I_D \cong 10\text{ A}$, $V_{GEN} = 10\text{ V}$, $R_g = 1\text{ }\Omega$	-	40	80	ns
Rise time	t_r		-	45	90	
Turn-off delay time	$t_{d(off)}$		-	85	170	
Fall time	t_f		-	45	90	
Drain-Source Body Diode Characteristics						
Continuous source-drain diode current	I_S	$T_C = 25\text{ }^\circ\text{C}$	-	-	487	A
Pulse diode forward current	I_{SM}		-	-	900	
Body diode voltage	V_{SD}	$I_S = 10\text{ A}$, $V_{GS} = 0\text{ V}$	-	0.7	1.1	V
Body diode reverse recovery time	t_{rr}	$I_F = 10\text{ A}$, $di/dt = 100\text{ A}/\mu\text{s}$, $T_J = 25\text{ }^\circ\text{C}$	-	105	210	ns
Body diode reverse recovery charge	Q_{rr}		-	310	620	nC
Reverse recovery fall time	t_a		-	64	-	ns
Reverse recovery rise time	t_b		-	41	-	

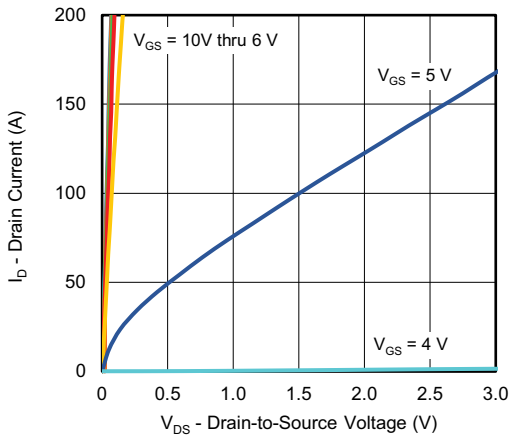
Notes

- a. Pulse test; pulse width $\leq 300\text{ }\mu\text{s}$, duty cycle $\leq 2\%$
b. Guaranteed by design, not subject to production testing

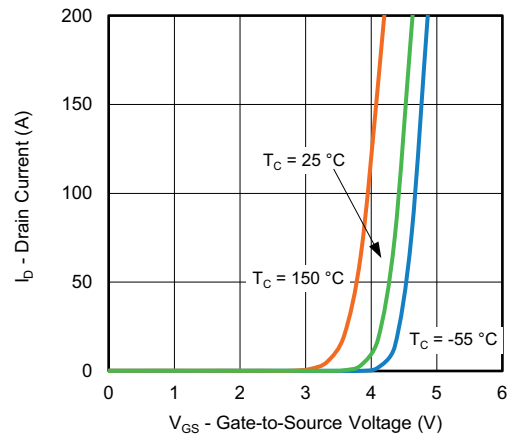
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



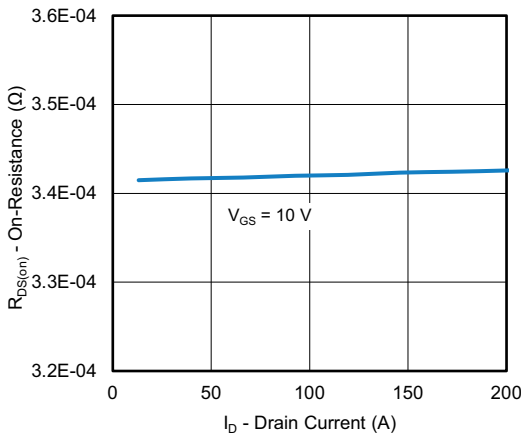
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



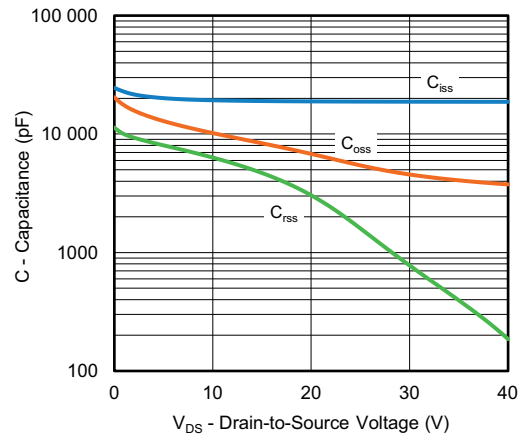
Output Characteristics



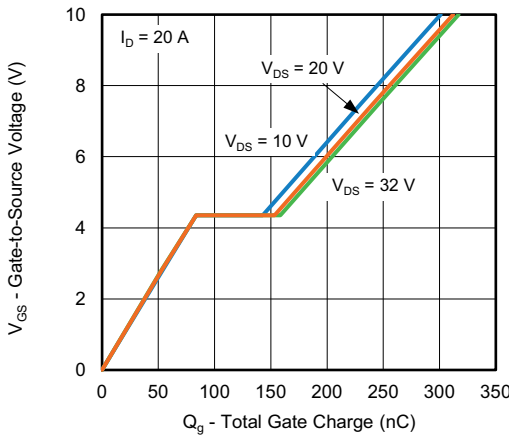
Transfer Characteristics



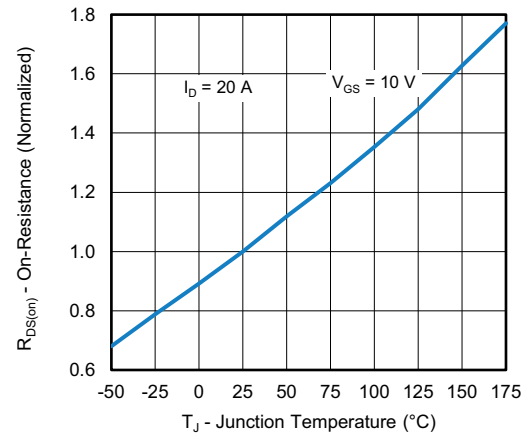
On-Resistance vs. Drain Current and Gate Voltage



Capacitance



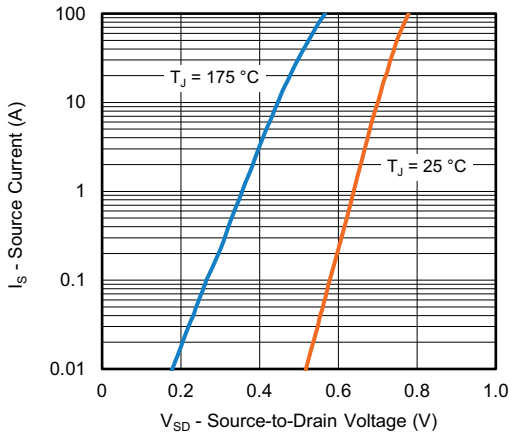
Gate Charge



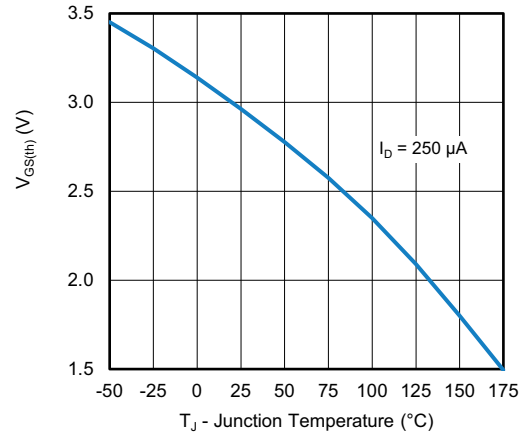
On-Resistance vs. Junction Temperature



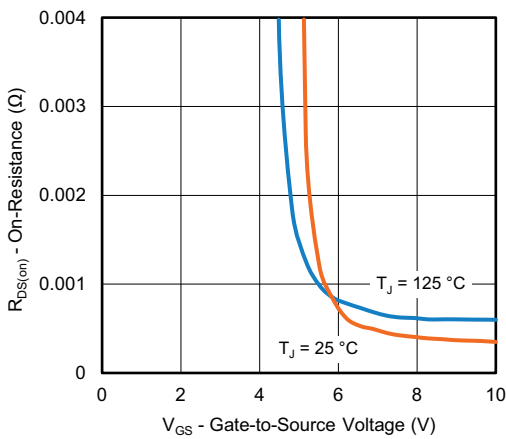
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



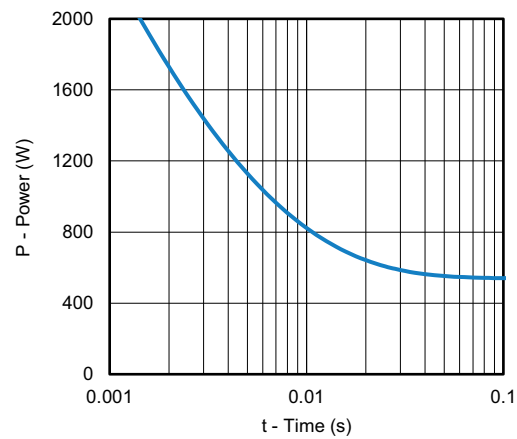
Source-Drain Diode Forward Voltage



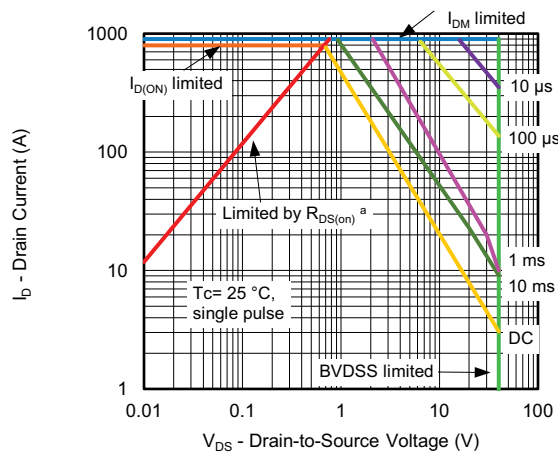
Threshold Voltage



On-Resistance vs. Gate-to-Source Voltage



Single Pulse Power, Junction-to-Case



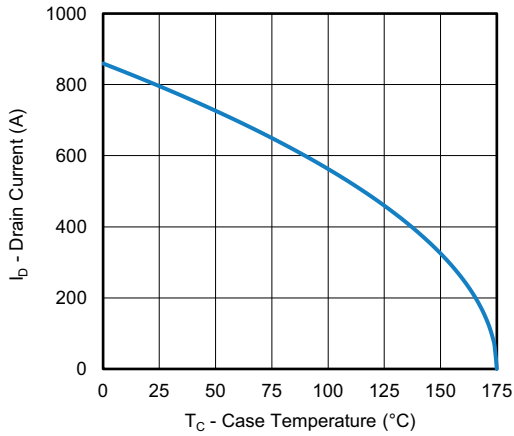
Safe Operating Area, Junction-to-Ambient

Note

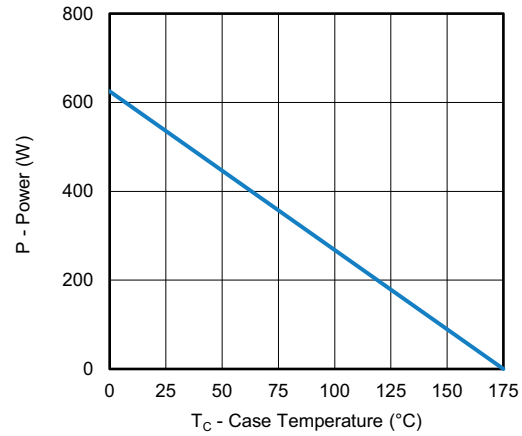
a. $V_{GS} >$ minimum V_{GS} at which $R_{DS(on)}$ is specified



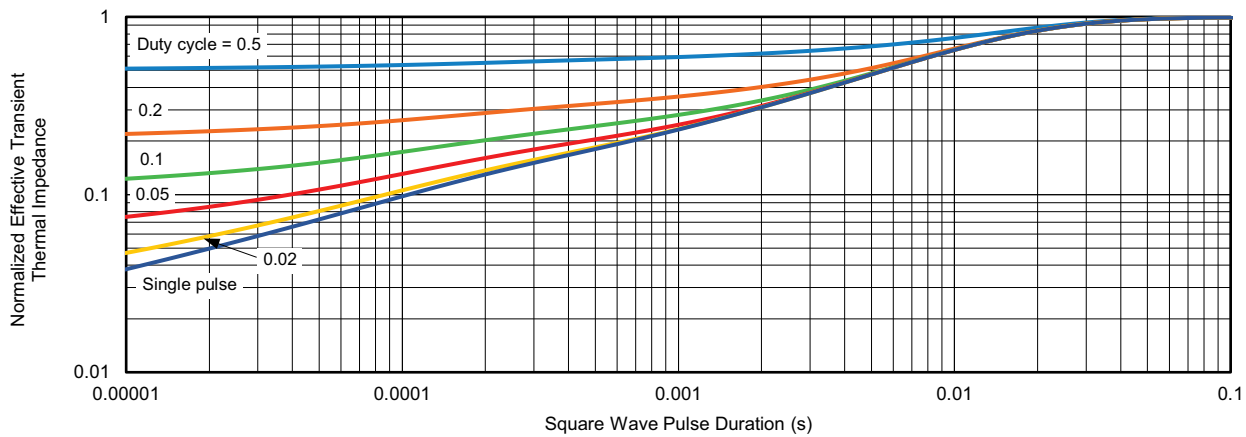
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



Current Derating ^a



Power, Junction-to-Case



Normalized Thermal Transient Impedance, Junction-to-Case

Note

- a. The power dissipation P_D is based on $T_{J \text{ max.}} = 150 \text{ °C}$, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit

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